

# MECHANICAL CASE OUTLINE

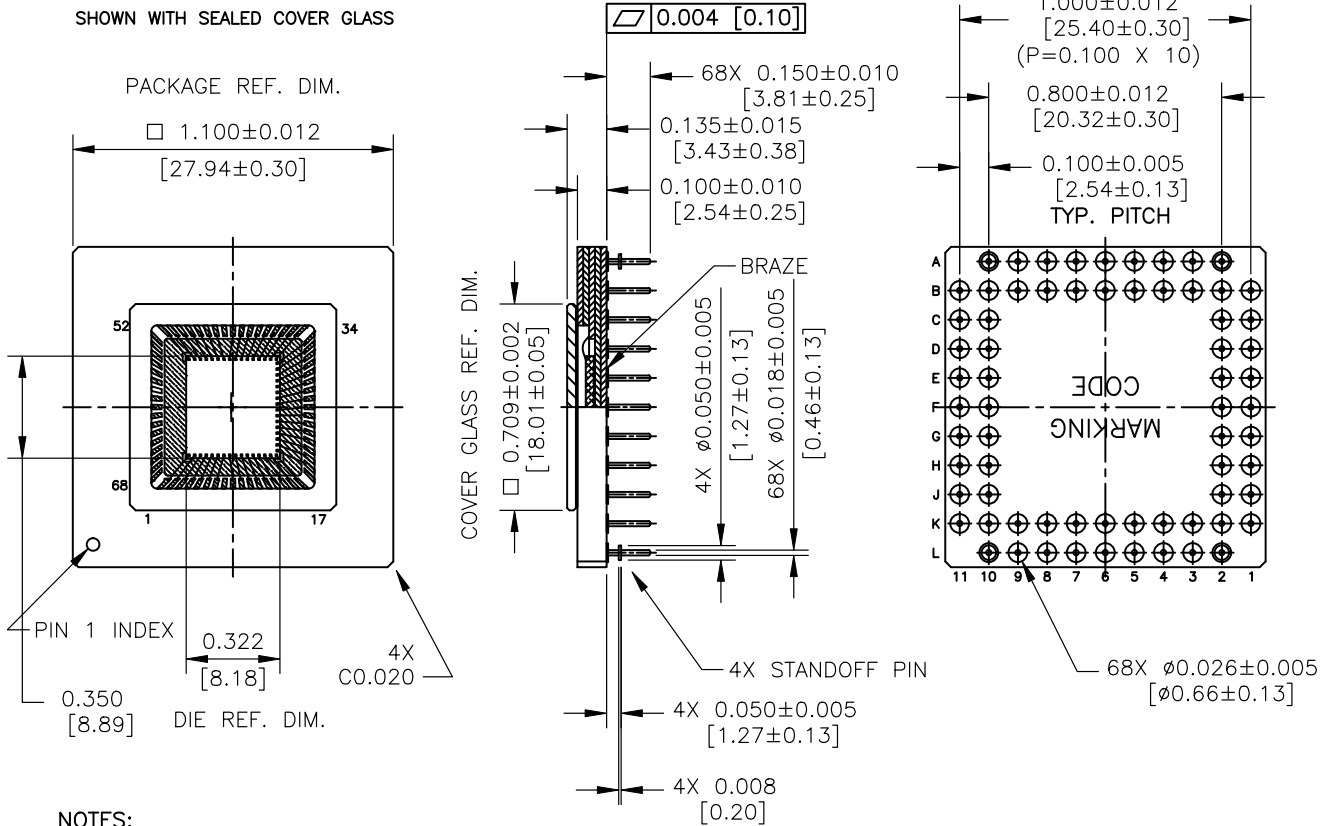
## PACKAGE DIMENSIONS

ON Semiconductor®



**CPGA68, 27.94x27.94**  
**CASE 107EP**  
**ISSUE O**

DATE 30 JUL 2014



**NOTES:**

- COVER GLASS IS VISUALLY ALIGNED OVER DIE – NO GUARANTEE OF LOCATION ACCURACY.

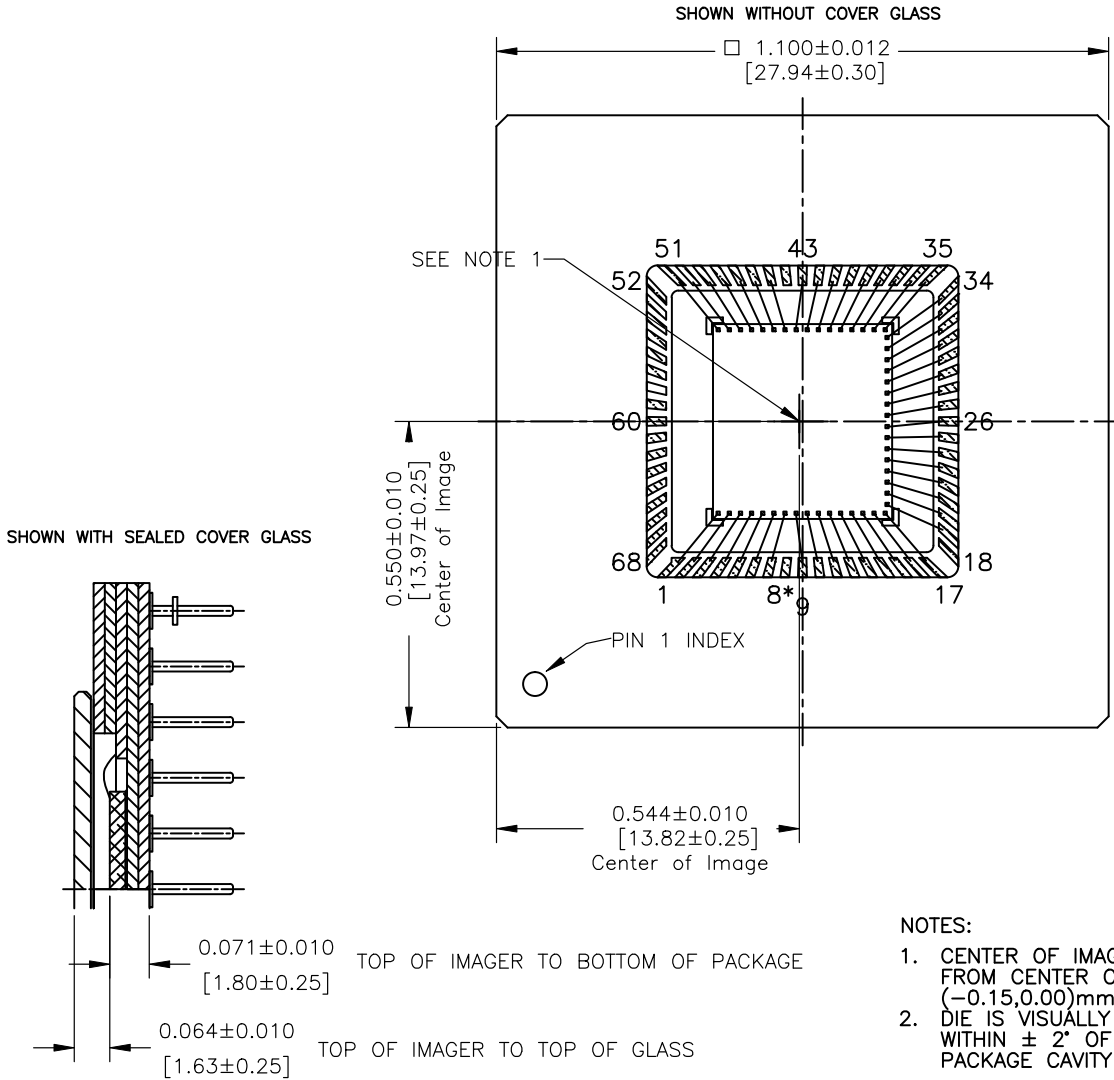
Dimensions in: Inches [mm]

|                         |                            |                                                                                                                                                                                  |
|-------------------------|----------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
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**NOTES:**

1. CENTER OF IMAGE AREA IS OFFSET FROM CENTER OF PACKAGE BY  $(-0.15, 0.00)$ mm NOMINAL.
2. DIE IS VISUALLY ALIGNED WITHIN  $\pm 2^\circ$  OF ANY PACKAGE CAVITY EDGE.

**Dimensions in: Inches [mm]**

|                         |                            |                                                                                                                                                                                  |
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